

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1 – 27. (canceled)

28. (currently amended) A system comprising

(a) ~~a plurality of bonders~~ first bonder for bonding semiconductor chips; ~~each bonder~~ having a calculating unit for manipulating data relating to a bonding operation, a memory unit for storing information relating to the bonding operation, and an optical unit for acquiring visual images relating to the bonding operation, ~~and an adaptive compensator for controlling the bonding operation;~~

(b) ~~and a communication means for providing communication between the calculating unit, the memory unit, and the optical unit of a bonder, and for providing communication among bonders~~ to a second bonder;

the second bonder having a calculating unit for manipulating data relating to a bonding operation, a memory unit for storing information relating to the bonding operation, and an optical unit for acquiring visual images relating to the bonding operation, an adaptive compensator for generating a corrected device program for controlling the bonding operation, and a communication means for providing communication between the calculating unit, the memory unit, and the optical unit of a bonder, and for providing communication to the first bonder;

(c) a semiconductor chip having a plurality of bondpads arranged on the semiconductor chip;

(d) a set of ~~group-segments for grouping the plurality~~ of bondpads of the semiconductor chip, each segment having a reference member related to ~~[[the]]~~ a number of bondpads in the segment and coordinates of the reference member and a visual representation of the segment;

- (e) a device program including information related to the semiconductor chip and the segments, the reference members, the coordinates of the reference members, and the visual representations, ~~stored in the memory unit of the~~ bonders;
 - (f) ~~a visual image file containing visual information of the segments acquired from the optical unit,~~ the device program stored in the memory unit of the first bonder and a copy of the device program stored in the second bonder;
 - (g) corrective data generated in the calculating unit of the second bonder relating the device program related to the semiconductor chip and the segments, including the reference members, the coordinates of the reference members, and the visual representations ~~and the visual information~~; and
 - (h) the adaptive compensator of the second bonder adaptive to compare information from the stored device program and the corrective data ~~receive the corrective data for controlling the bonding operation~~; and
a bond program corrector for generating a corrected device program relating to the semiconductor chip and the segments, including the reference members, the coordinates of the reference members, and the visual representations, suitable for aiding the second bonder for the bonding operation.
29. (currently amended) A method for bonding a semiconductor chips with a plurality of bonders; comprising
- (a) providing a first bonder ~~plurality of bonders; each bonder~~ having a calculating unit for manipulating data relating to a bonding operation, a memory unit for storing information relating to the bonding operation, an optical unit for acquiring visual images relating to the bonding operation, ~~and an adaptive compensator for controlling the bonding operation~~; and a
 - (b) ~~providing~~ a communication means for providing communication between the calculating unit, the memory unit, and the optical unit of a bonder, and for providing communication ~~among bonders~~ to a second bonder;

providing the second bonder having a calculating unit for manipulating data relating to a bonding operation, a memory unit for storing information relating to the bonding operation, and an optical unit for acquiring visual images relating to the bonding operation, an adaptive compensator for generating a corrected device program for controlling the bonding operation, and a communication means for providing communication between the calculating unit, the memory unit, and the optical unit of a bonder, and for providing communication to the first bonder;

(e) providing a semiconductor chip having a plurality of bondpads arranged on the semiconductor chip;

(d) grouping the plurality of bondpads of the semiconductor chip into a plurality of segments, each segment having a reference member related to the bondpads in the segment, coordinates of the reference member and a visual representation of the segment;

(e) generating a device program including information related to the displacement of the bondpads on the semiconductor chip and related to the segments that group the bondpads, the reference members, the coordinates of the reference members, and the visual representations;

(f) storing the device program in the memory units of the first bonder and a copy of the device program in the second bonder; ~~bonders;~~

(g) placing a semiconductor chip of the device program on ~~[[a]]~~ the second bonder having the device program;

(h) capturing visual images of the segments of the bondpads on the semiconductor chip including the reference members and their coordinates;

(i) communicating the visual images to the calculating unit;

(j) communicating the device program to the calculating unit;

(k) generating corrective data in the calculating unit of the second bonder based on the device program and the visual images;

the adaptive compensator comparing the stored device program and the corrective data ~~receive the corrective data for controlling the bonding operation~~

generating a corrected device program in the bond program corrector relating to the semiconductor chip and the segments, including the reference member, new coordinates of the reference members, and the visual representations;

(t) communicating the ~~corrective data~~ corrected device program to the control unit of the second bonder for controlling the bonding operation; and

(m) performing the bonding of the semiconductor chip based on the corrected device program ~~corrective data~~.